12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20130418000
Qualification of Cu as Additional Wire Base Metal Option for Select QFP and BGA Package Devices
Change Notification / Sample Request

Date: 5/24/2013
To: Digi-Key PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 90 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20130418000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TMS320C6204ZHK200	null
TMS320C6205DZHK200	null
TMS320C6205GHKA200	null
TMS320C6205ZHK200	null
TMS320C6421ZWT4	null
TMS320C6421ZWT5	null
TMS320C6421ZWT6	null
TMS320C6424ZWT4	null
TMS320C6424ZWT5	null
TMS320C6424ZWT6	null
TMS320DM357ZWT	null
TMS320DM6431ZWT3	null
TMS320DM6433ZWT4	null
TMS320DM6433ZWT5	null
TMS320DM6435ZWT5	null
TMS320DM6435ZWT6	null
TMS320DM6437ZWT4	null
TMS320DM6437ZWT6	null
TMS320DM6441AZWT	null
TMS320DM6441BZWT	null
TMS320DM6443AZWT	null
TMS320DM6446AZWT	null
TMS320DM6446AZWTA	null
TMS320DM6446BZWT8	null
TMS320F2808GGMA	null
TMS320F2808GGMS	null
TMS320F2808ZGMS	null
TMS320F2809GGMS	null
TMS320F2809ZGMA	null
TMS320F2809ZGMS	null
TMS320F2812GHHA	null
TMS320F2812ZHHA	null
TMS320F2812ZHHS	null
TMS320F28335ZHHA	null
TMS320R2812GHHS	null
TMS320VC33PGE150	null
TMS320VC33PGEA120	null
TMS320VC5407GGU	null
TMS320VC5410AZGU12	null
TMS320VC5416ZGU160	null
TMS320VC5441AGGU	null
TMS320VC5441ZGU	null
TMS320DM6443ZWT	null
TMS320F2801GGMA	null
TMS320F2801GGMS	null
TMS320F2801ZGMA	null
TMS320F2801ZGMS	null
TMS320F2802ZGMA	null
TMS320F2802ZGMS	null
TMS320F2806GGMA	null
TMS320F2806GGMS	null

TMS320F2806ZGMA	null
TMS320F2806ZGMS	null
TMS320F2808ZGMA	null
TMS320F2809GGMA	null
TMS320VC5402AZGU16	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20130418000	**PCN Date:**	05/24/2013
Title:	Qualification of Cu as Additional Wire Base Metal Option for Select QFP and BGA Package Devices		
Customer Contact:	PCN_ww_admin_team@list.ti.com	**Phone:**	+1(214)480-6037
Dept:	Quality Services		
Proposed 1st Ship Date:	08/24/2013	**Estimated Sample Availability:**	Date provided at sample request.

Change Type:

☐	Assembly Site	☐	Assembly Process	☒	Assembly Materials

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of Cu as an additional bond wire option for select devices listed in "Product affected" section below. Devices will remain in current assembly facility. Following identifies the material differences for the Product Affected list:

- Group 1 – Devices that will have no change on wire diameter
- Group 2 – Devices that will have the following wire diameter change

Material Set	Current Assembly Au wire	Cu Bond wire option
Wire diam (Mils)	0.96	0.80

Reason for Change:

Continuity of supply.

1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties
2) Maximize flexibility within our Assembly/Test production sites.
3) Cu is easier to obtain and stock

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None.

Changes to product identification resulting from this PCN:

None.

Product Affected: Group 1- Devices that will have no change on wire diameter

D16782PGE100	F731891PDVG4	TMS320VC33PGE120G4	TMS320VC33PGEA120
D36780PGE100	TMS320VC33PGE120	TMS320VC33PGE150	TMS320DM335DZCE135
TMS320DM335DZCE216	TMS320DM335DZCE270	TMS320DM355DZCEA21	DM355SDZCEA216

Product Affected: Group 2 – Devices that will have wire diameter change			
C6421SURFVOZWT4	M6446AZWTHAIER	TMSDM6446AZWT-COM	TMS320F2809GGMS
C6421SURFVOZWT4B	M6446AZWTHAIERIN	TNETV1645ZWT	TMS320F2809ZGMA
C6421SURFVOZWT5	M6446AZWTHISENSE	TNETV1647GSTZWT	TMS320F2809ZGMS
C6421SURFVOZWT5B	M6446AZWTPAV	TNETV2664ACLZWT	TMS320F2812GHHA
C6421SURFVOZWT6	M6446AZWTPM	TNETV2664FIBZWT	TMS320F2812GHHAR
C6421SURFVOZWT6B	M6446AZWTSKYWORTH	TNETV2664FIDZWT	TMS320F2812GHHS
C6424SURFVDZWT4	M6446AZWTTONGLI	TNETV2665FIBZWT4	TMS320F2812ZHHA
C6424SURFVDZWT4B	M6446BZWTAVMEAWOX	TNETV2665FIBZWT6	TMS320F2812ZHHAR
C6424SURFVDZWT5	M6446ZWTAVMEAWOX	TNETV2665FIBZWT7	TMS320F2812ZHHS
C6424SURFVDZWT5B	M6446ZWTAVMEHIMEDI	TNETV2665FIBZWTA7	TMS320F28232ZHHA
C6424SURFVDZWT6	M6446ZWTAVMEMOTO	TNETV2665FIDZWT4	TMS320F28234ZHHA
C6424SURFVDZWT6B	M6446ZWTHAIERIN	TNETV2665FIDZWT6	TMS320F28235ZHHA
C6424SURFVOZWT4	M6446ZWTHAIERSF	TNETV2665FIDZWT7	TMS320F28332ZHHA
C6424SURFVOZWT4B	M6446ZWTHISENSE	TNETV2665FIDZWTA7	TMS320F28334ZHHA
C6424SURFVOZWT5	M6446ZWTJIUZHOU	TNETV2665VIDZWT4	TMS320F28335ZHHA
C6424SURFVOZWT5B	M6446ZWTSKYWOTH	TNETV2665VIDZWT6	TMS320R2812GHHA
C6424SURFVOZWT6	M6446ZWTSREU	TNETV2665VIDZWT7	TMS320R2812GHHS
C6424SURFVOZWT6B	M6446ZWTSTYLE	TNETV2665VIDZWTA7	TMS320R2812ZHHA
DM350HZWK-ACM	M6446ZWTSYS	TNETV2665ZWT4	TMS320R2812ZHHS
DM350HZWK-KD17	M6446ZWTVTAILYN	TNETV2665ZWT6	TMS320SP5410AGGU12
DM350HZWK-KD53	SN3490586	TNETV2665ZWT7	TMS320SP5410AZGU12
DM350HZWKMINTON	TMS320C6421ZWT4	TNETV2665ZWTA7	TMS320VC5402AGGU16
DM350LZWK-ACM	TMS320C6421ZWT5	TNETV2666ACLZWT	TMS320VC5402AZGU16
DM350LZWKAB	TMS320C6421ZWT6	TNETV2666FIBZWT	TMS320VC5404GGU
DM350LZWKAO	TMS320C6421ZWT7	TNETV2666FIDZWT	TMS320VC5407GGU
DM350LZWKMINTON	TMS320C6421ZWTL	TNETV2666INZWT	TMS320VC5407ZGU
DM350LZWKPHIL	TMS320C6424ZWT4	TNETV2667FIBZWT	TMS320VC5409AGGU12
DM350UHZWKHD	TMS320C6424ZWT5	TNETV2667FIBZWTA	TMS320VC5409AGGU16
DM350ULZWKMINTON	TMS320C6424ZWT6	TNETV2667FIDZWT	TMS320VC5409AZGU12
DM6437ZWT6-IOIMAGE	TMS320C6424ZWT7	TNETV2667ZWT	TMS320VC5409AZGU16
DM6443ADB6C3126MP	TMS320C6424ZWTA7	TNETV6446AINZWT	TMS320VC5410AGGU12
DM6443DB6C3125MP	TMS320C6424ZWTD7	TNETV6446AINZWT8	TMS320VC5410AGGU16
DM6446AAB6C4130VD	TMS320C6424ZWTL	D36155ZGU160	TMS320VC5410AZGU12
DM6446ANB6C2127VC	TMS320DH6435ZWT6	DE111001ZHHA	TMS320VC5410AZGU16
DM6446APB6C6128ED	TMS320DM350HZWK	DE129003ZHHA	TMS320VC5416GGU120
DM6446AZWTKEDACOM	TMS320DM350HZWKR	DE129005ZHHA	TMS320VC5416GGU160
DM6446EB6C2110VS	TMS320DM350LZWK	DEF01000ZHHA	TMS320VC5416ZGU120
DM6446GB6C0121MV	TMS320DM350UHZWK	DFDF2812GHHA	TMS320VC5416ZGU160
DM6446IB6C0107VS	TMS320DM350ULZWK	DFDF2812ZHHA	TMS320VC5441AGGU
DM6446IB6C4112VS	TMS320DM357ZWT	DFDF2812ZHHAR	TMS320VC5441AZGU
DM6446LB6C3108VS	TMS320DM6431ZWT3	DRA1410AHBZ	TMS320VC5441AZGUZE
DM6446LB6C3109VS	TMS320DM6433ZWT4	DVC5416ZGU160IDWLD	TMS320VC5441GGU
DM6446MICD1C2104SC	TMS320DM6433ZWT5	F741747GHC	TMS320VC5441GGULU
DM6446MLTD1C2105ST	TMS320DM6433ZWT6	F741747ZHC	TMS320VC5441GGUR
DM6446NB6C5123NP	TMS320DM6433ZWT7	F741894GHC	TMS320VC5441GGURZE
DM6446RB6C6122VP	TMS320DM6433ZWTL	F741894ZHC	TMS320VC5441GGUSON
DM6446RB6C6124VP	TMS320DM6435EZWT6	F741999AZGU	TMS320VC5441GGUZE
DM6446SB6C6117MD	TMS320DM6435ZWT4	TMS320ACLAGGU	TMS320VC5441GUDIT
DM6446ZB6C3111VP	TMS320DM6435ZWT4CX	TMS320ACLBZGU	TMS320VC5441GURDIT

DM644NECED1C2102VC	TMS320DM6435ZWT5	TMS320ACLGGU	TMS320VC5441ZGU
F761541AZVLR	TMS320DM6435ZWT5CX	TMS320ACLZGU	TMS320VC5441ZGUZE
KROGUDPDM6446AZWT	TMS320DM6435ZWT6	TMS320C54CSTGGU	TMS32C6205DGHKA200
KROGUDPDM6446BZWT	TMS320DM6435ZWT6CX	TMS320C54CSTZGU	TMS32C6205DZHKA200
M350ZWKDPFING	TMS320DM6435ZWT7	TMS320C54V90BGGU	TNETV2840ENGGU
M6435CZWTSLG	TMS320DM6435ZWTL	TMS320C6204GHK200	TNETV2840ENZGU
M6441AZWTBJSF	TMS320DM6437ZWT4	TMS320C6204GHKA200	TNETV2840FIBGGU
M6441AZWTHAIERIN	TMS320DM6437ZWT5	TMS320C6204ZHK200	TNETV2840FIDGGU
M6441AZWTHTSPHI	TMS320DM6437ZWT6	TMS320C6204ZHKA200	TNETV2840FIDGGUA
M6441AZWTIFLYTECH	TMS320DM6437ZWT7	TMS320C6205DGHK200	TNETV2840FIDZGU
M6441AZWTMICRO	TMS320DM6437ZWTL	TMS320C6205DZHK200	TNETV2840FIRGGU
M6441AZWTPM	TMS320DM6441AZWT	TMS320C6205GHK200	TNETV2840FISGGU
M6441AZWTSEED	TMS320DM6441BZWT	TMS320C6205GHKA200	TNETV2840FISZGU
M6443AZWTBJSF	TMS320DM6442AZWT	TMS320C6205ZHK200	TNETV2840FNBGGU
M6443AZWTHAIER	TMS320DM6443AZWT	TMS320DA150GGU160	TNETV2840FNBZGU
M6443AZWTKAITIAN	TMS320DM6443AZWTB	TMS320DA150ZGU160	TNETV2840FNDGGU
M6443AZWTPM	TMS320DM6443BZWT	TMS320DA150ZGUR120	TNETV2840FNRGGU
M6443BZWTAVMEAWOX	TMS320DM6443PAVZWT	TMS320DRE201GGU160	TNETV2840FNSGGU
M6443ZWTAIRTIES	TMS320DM6443ZWT	TMS320F28015ZGMA	TNETV2840FNSGGUA
M6443ZWTAMI	TMS320DM6443ZWTJET	TMS320F2801GGMA	TNETV2840FNSZGU
M6443ZWTAVMEAWOX	TMS320DM6444AZWT	TMS320F2801GGMS	TNETV2840GGU
M6443ZWTAVMEHIMEDI	TMS320DM6444AZWTR	TMS320F2801ZGMA	TNETV2840GGUA
M6443ZWTAVMEKONKA	TMS320DM6444ZWTR	TMS320F2801ZGMS	TNETV2840MODGGU
M6443ZWTAVMEMEDIAE	TMS320DM6446AZWT	TMS320F2802GGMA	TNETV2840VFIDGGU
M6443ZWTAVMEYUXING	TMS320DM6446AZWTA	TMS320F2802GGMS	TNETV2840VIBGGU
M6443ZWTAVMEZTE	TMS320DM6446BZWT	TMS320F2802ZGMA	TNETV2840VIDGGU
M6443ZWTING	TMS320DM6446BZWT7	TMS320F2802ZGMS	TNETV2840VIRGGU
M6443ZWTJET	TMS320DM6446BZWT8	TMS320F2806GGMA	TNETV2840VISGGU
M6443ZWTVTAILYN	TMS320DM6446BZWTA	TMS320F2806GGMS	TNETV2840VNBGGU
M6443ZWTWNC	TMS320DM6446PAVZWT	TMS320F2806ZGMA	TNETV2840VNDGGU
M64444ZWTRAVM	TMS320DM6446ZWT	TMS320F2806ZGMS	TNETV2840VNDZGU
M6444AZWTAIRTIES	TMS320DM6447AZWT	TMS320F2808GGMA	TNETV2840VNRGGU
M6444AZWTAMI	TMS320MED6446ZWT	TMS320F2808GGMS	TNETV2840VNSGGU
M6444ZWTAVM	TMS320VER6446ZWT	TMS320F2808ZGMA	TNETV2840ZGU
M6446AZWTBESTA	TMSDDVI6441AZWTHV	TMS320F2808ZGMS	TNETV2842VNDGGU
M6446AZWTBJSF	TMSDDVI6446AZWTHV	TMS320F2809GGMA	

Qualification Data for devices in Group 1: Approved 04/05/2013

Qual Vehicle 1: F741900APFB (MSL 3-260C)					
Package Construction Details					
Assembly Site:	TAI	Mold Compound:	4205442		
# Pins-Designator, Family:	48-PFB, TQFP	Mount Compound:	4042504		
Lead frame (Finish, Base):	NiPdAu	Bond Wire:	0.96Mil Cu		
Qualification: ☐ **Plan** ☒ **Test Results**					
Reliability Test	Conditions	Sample Size/Fail			
		Lot#1	Lot#2	Lot#3	
Manufacturability		Pass	Pass	Pass	
**Thermal Shock	-65/150C (1000Cyc)	77/0	77/0	77/0	
**Autoclave	121C (384Hrs)	77/0	77/0	77/0	
**High Temp. Storage Bake	170C (1000 hrs)	77/0	77/0	77/0	
**T/C -65C/150C	-65C/+150C (2000 Cyc)	77/0	77/0	77/0	
Moisture Sensitivity	Level 3-260C	12/0	12/0	12/0	
Notes **- Preconditioning sequence: Level 3-260C.					

Qual Vehicle 2: TL16C550DPTR (MSL 3-260C)			
Package Construction Details			
Assembly Site:	TAI	Mold Compound:	4205442
# Pins-Designator, Family:	48-PT, LQFP	Mount Compound:	4042504
Lead frame (Finish, Base):	NiPdAu	Bond Wire:	0.96Mil Cu
Qualification: ☐ **Plan** ☒ **Test Results**			

Reliability Test	Conditions	Sample Size/Fail
Manufacturability		Pass
**Thermal Shock	-65/150C (1000Cyc)	77/0
**Autoclave	121C (384Hrs)	77/0
**High Temp. Storage Bake	170C (1000 hrs)	77/0
**T/C -65C/150C	-65C/+150C (1500 Cyc)	77/0
Moisture Sensitivity	Level 3-260C	12/0
Notes **- Preconditioning sequence: Level 3-260C.		

Qual Vehicle 3: TL16C752BPT (MSL 3-260C)			
Package Construction Details			
Assembly Site:	TAI	Mold Compound:	4205442
# Pins-Designator, Family:	48-PT, LQFP	Mount Compound:	4042504
Lead frame (Finish, Base):	NiPdAu	Bond Wire:	0.96Mil Cu
Qualification: ☐ **Plan** ☒ **Test Results**			

Reliability Test	Conditions	Sample Size/Fail
Manufacturability		Pass
**Thermal Shock	-65/150C (1000Cyc)	77/0
**Autoclave	121C (384Hrs)	77/0
**High Temp. Storage Bake	170C (1000 hrs)	77/0
**T/C -65C/150C	-65C/+150C (2000 Cyc)	77/0
Moisture Sensitivity	Level 3-260C	12/0
Notes **- Preconditioning sequence: Level 3-260C.		

Qual Vehicle 4: TPS5130PTR (MSL 1-260C)			
Package Construction Details			
Assembly Site:	TAI	Mold Compound:	4205442
# Pins-Designator, Family:	48-PT, LQFP	Mount Compound:	4042504
Lead frame (Finish, Base):	NiPdAu	Bond Wire:	0.96Mil Cu
Qualification: ☐ **Plan** ☒ **Test Results**			

Reliability Test	Conditions	Sample Size/Fail
Manufacturability		Pass
**Thermal Shock	-65/150C (1000Cyc)	77/0
**Autoclave	121C (384Hrs)	77/0
**High Temp. Storage Bake	170C (1000 hrs)	77/0
**T/C -65C/150C	-65C/+150C (2000 Cyc)	77/0
Moisture Sensitivity	Level 1-260C	12/0
Notes **- Preconditioning sequence: Level 1-260C.		

Qual Vehicle 5: TSB12LV21BPGF (MSL 3-250C)			
Package Construction Details			
Assembly Site:	TAI	Mold Compound:	4205442
# Pins-Designator, Family:	176-PGF, LQFP	Mount Compound:	4042504
Lead frame (Finish, Base):	NiPdAu	Bond Wire:	0.96Mil Cu
Qualification: ☐ **Plan** ☒ **Test Results**			

Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
Manufacturability		Pass	Pass	Pass
**Thermal Shock	-65/150C (1000Cyc)	77/0	77/0	77/0
**Autoclave	121C (384Hrs)	77/0	77/0	77/0
**High Temp. Storage Bake	170C (1000 hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (2000 Cyc)	77/0	77/0	77/0
Notes **- Preconditioning sequence: Level 3-250C.				

Qual Vehicle 6: UCC5696PN (MSL 3-260C)			
Package Construction Details			
Assembly Site:	TAI	Mold Compound:	4205442
# Pins-Designator, Family:	80-PN, LQFP	Mount Compound:	4042504
Lead frame (Finish, Base):	NiPdAu	Bond Wire:	0.96Mil Cu
Qualification: ☐ **Plan** ☒ **Test Results**			

Reliability Test	Conditions	Sample Size/Fail	
		Lot#1	Lot#2
Manufacturability		Pass	Pass
**Thermal Shock	-65/150C (500Cyc)	77/0	77/0
**T/C -65C/150C	-65C/+150C (1000 Cyc)	77/0	77/0
Moisture Sensitivity	Level 3-250C	12/0	12/0
Notes **- Preconditioning sequence: Level 3-260C.			

Qualification Data for devices in Group 2: Approved 04/05/2013

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle 1: F761536AZZD (MSL 3-260C)

Package Construction Details

Assembly Site:	PHI (TIPI)	Mold Compound:	4203565
# Pins-Designator, Family:	179-ZZD, BGA	Mount Compound:	4111062
Solder Ball composition	SnAgCu	Bond Wire:	0.80Mil Cu

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
** HAST	110C/85%RH (264hrs)	77/0	77/0	77/0
**Unbiased HAST	110C/85%RH (384hrs)	77/0	77/0	77/0
**High Temp. Storage Bake	150C (1008 hrs)	77/0	77/0	77/0
**T/C -55C/125C	-55C/+125C (1000 Cyc)	77/0	77/0	77/0

Notes **- Preconditioning sequence: Level 3-260C.

Qual Vehicle 2: TVAIC3106IZQER (MSL 3-260C)

Package Construction Details

Assembly Site:	PHI (TIPI)	Mold Compound:	4205867
# Pins-Designator, Family:	80-ZCE, BGA	Mount Compound:	4206198
Solder Ball composition	SnAgCu	Bond Wire:	0.80Mil Cu

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
** Unbiased HAST	110C/85%RH (264hrs)	77/0	77/0	77/0
**High Temp. Storage Bake	150C (1000 hrs)	77/0	77/0	77/0
**T/C -55C/125C	-55C/+125C (2000 Cyc)	77/0	77/0	77/0

Notes **- Preconditioning sequence: Level 3-260C.

Qual Vehicle 3: F761990B5ZDU (MSL 4-260C)

Package Construction Details

Assembly Site:	PHI (TIPI)	Mold Compound:	4208515
# Pins-Designator, Family:	376-ZDU, BGA	Mount Compound:	4205412
Solder Ball composition	SnAgCu	Bond Wire:	0.80Mil Cu

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
** Biased HAST	110C/85%RH (264hrs)	26/0	26/0	26/0
**Unbiased HAST	110C/85%RH (96hrs)	77/0	77/0	77/0
**High Temp. Storage Bake	150C (1000 hrs)	77/0	77/0	77/0
**T/C -55C/125C	-55C/+125C (1000 Cyc)	77/0	77/0	77/0

Notes **- Preconditioning sequence: Level 4-260C.

Qual Vehicle 4: TMS320DM6446BZWT8 (MSL 3-260C)			
Package Construction Details			
Assembly Site:	PHI (TIPI)	Mold Compound:	4208515
# Pins-Designator, Family:	361-ZWT, BGA	Mount Compound:	4205412
Solder Ball composition	SnAgCu	Bond Wire:	0.80Mil Cu

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fail	
		Lot#1	Lot#2
** Biased HAST	110C/85%RH (264hrs)	90/0	90/0
**Unbiased HAST	110C/85%RH (96hrs)	90/0	90/0
**High Temp. Storage Bake	150C (2000 hrs)	90/0	90/0
**T/C -55C/125C	-55C/+125C (1000 Cyc)	90/0	90/0
Notes **- Preconditioning sequence: Level 3-260C.			

Qual Vehicle 5: F761516ZAV (MSL 3-260C)			
Package Construction Details			
Assembly Site:	PHI (TIPI)	Mold Compound:	4208515
# Pins-Designator, Family:	289-ZAV, BGA	Mount Compound:	4073505
Solder Ball composition	SnAgCu	Bond Wire:	0.80Mil Cu

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
**T/C -55C/125C	-55C/+125C (1000 Cyc)	90/0	90/0	90/0
Manufacturability		Pass	Pass	Pass
Notes **- Preconditioning sequence: Level 3-260C.				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com